



Printed Circuit Boards  
Interconnection Carriers

**PRINTED CIRCUIT BOARDS**

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**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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04	163	FR4	35	L41.35	P18	S1
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columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

04\_163\_FR4\_35\_L41.35\_p18\_s1

Layers	in $\mu$	Material	Build-Up	Assembly
Layer-1	35 $\mu$	Copper		B
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
Layer-2	35 $\mu$	Copper		A1
	410 $\mu$	L-FR4		
Layer-3	35 $\mu$	Copper		B
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
Layer-99	35 $\mu$	Copper		B